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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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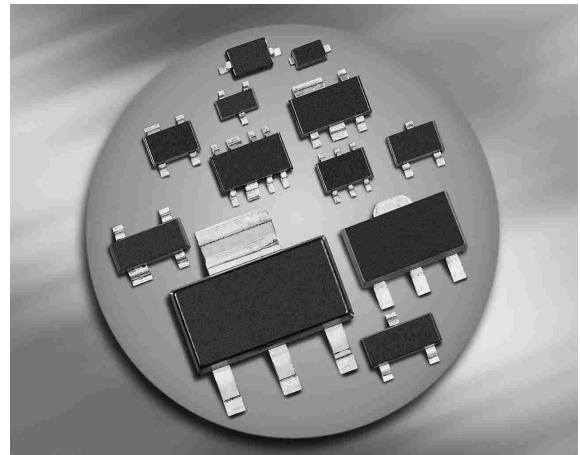
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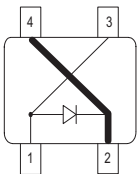


Silicon RF Switching Diode

- Designed for use in shunt configuration in high performance RF switches
- High shunt signal isolation
- Low shunt insertion loss
- Optimized for short - open transformation using $\lambda/4$ lines
- Pb-free (RoHS compliant) package



BAR81W



Type	Package	Configuration	L_S (nH)	Marking
BAR81W	SOT343	single shunt-diode	0.15*	BBs

* series inductance chip to ground

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	30	V
Forward current	I_F	100	mA
Total power dissipation $T_S \leq 138^\circ\text{C}$	P_{tot}	100	mW
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 120	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

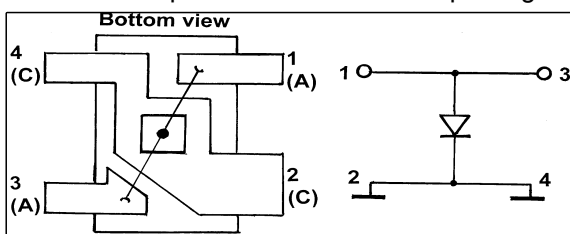
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current $V_R = 20\text{ V}$	I_R	-	-	20	nA
Forward voltage $I_F = 100\text{ mA}$	V_F	-	0.93	1	V

AC Characteristics

Diode capacitance $V_R = 1\text{ V}, f = 1\text{ MHz}$ $V_R = 3\text{ V}, f = 1\text{ MHz}$	C_T	-	0.6	1	pF
Forward resistance $I_F = 5\text{ mA}, f = 100\text{ MHz}$	r_f	-	0.7	1	Ω
Charge carrier life time $I_F = 10\text{ mA}, I_R = 6\text{ mA}$, measured at $I_R = 3\text{ mA}$, $R_L = 100\ \Omega$	τ_{rr}	-	80	-	ns
I-region width	W_I	-	3.5	-	μm
Shunt Insertion loss ¹⁾ $I_F = 10\text{ mA}, f = 1.89\text{ GHz}$	I_L	-	30	-	dB
Shunt isolation ¹⁾ $V_R = 3\text{ V}, f = 1.89\text{ GHz}$	I_{SO}	-	0.7	-	

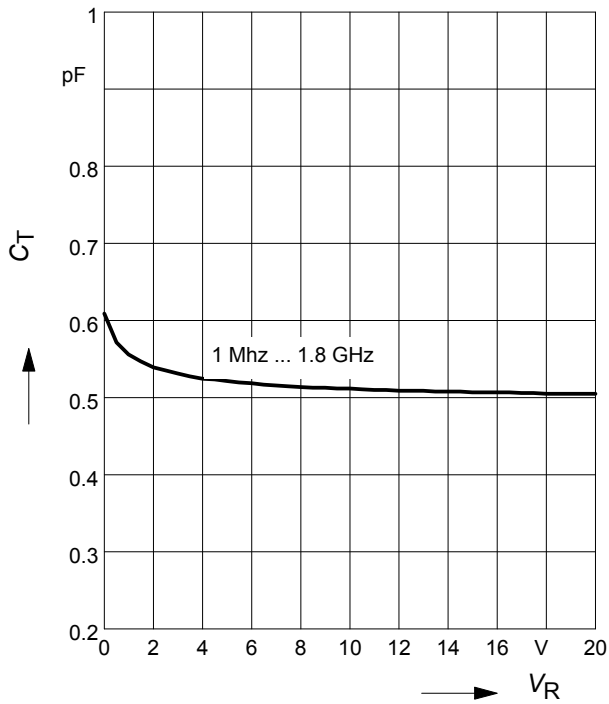
Configuration of the shunt-diode

- A perfect ground is essential for optimum isolation
- The anode pins should be used as passage for RF


¹For more information please refer to Application Note 049.

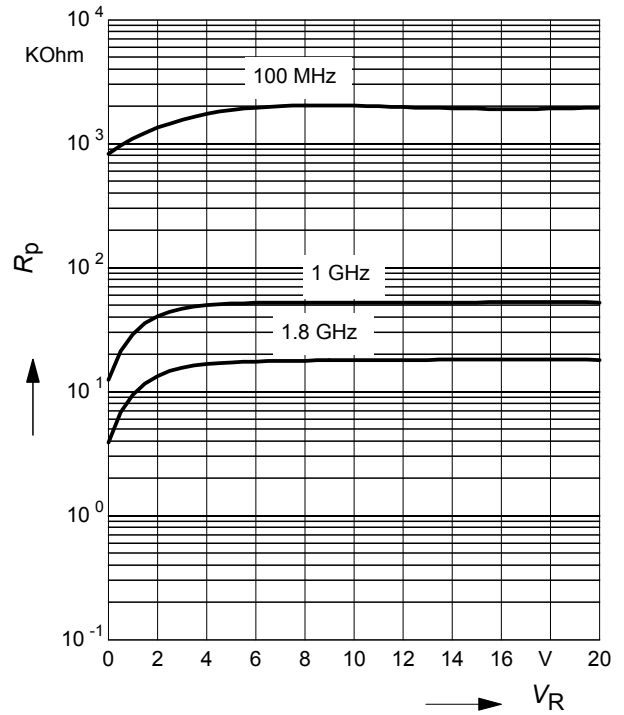
Diode capacitance $C_T = f(V_R)$

$f = \text{Parameter}$



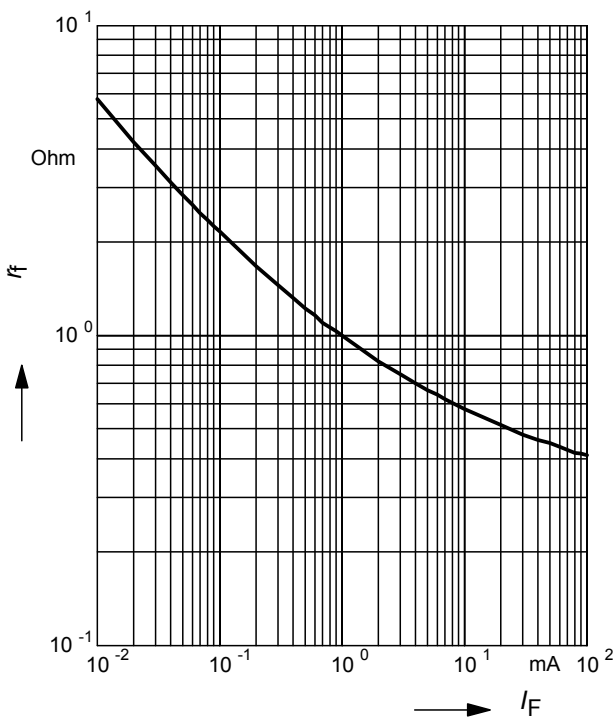
Reverse parallel resistance $R_P = f(V_R)$

$f = \text{Parameter}$



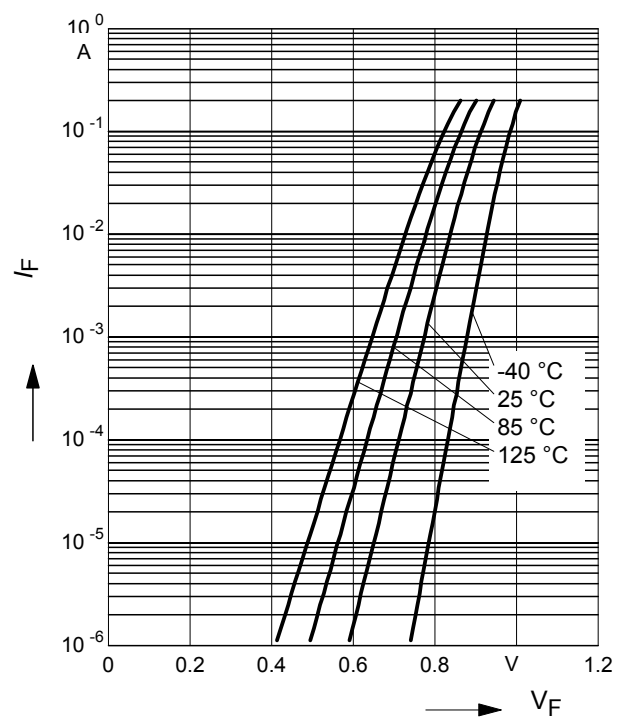
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$



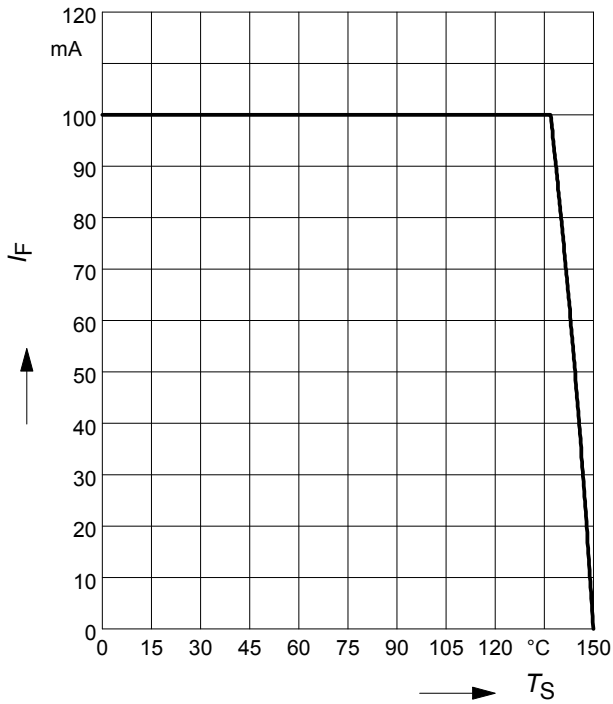
Forward current $I_F = f(V_F)$

$T_A = \text{Parameter}$



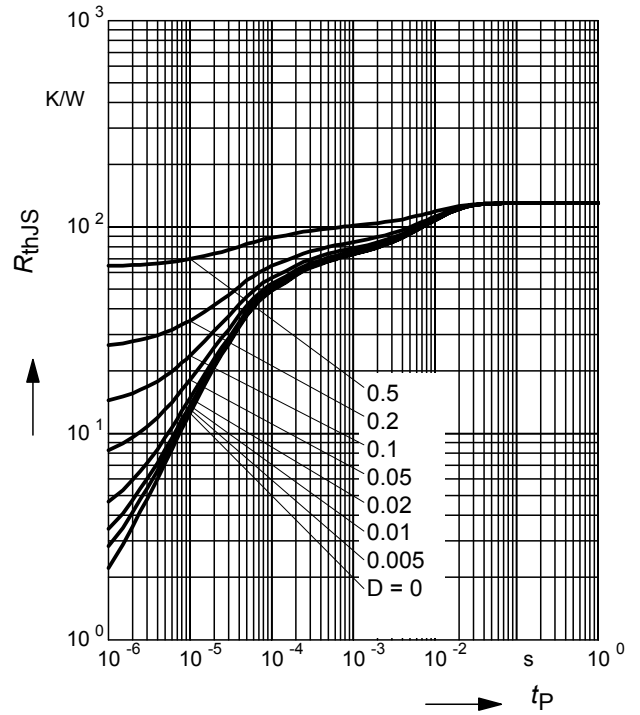
Forward current $I_F = f(T_S)$

BAR81W



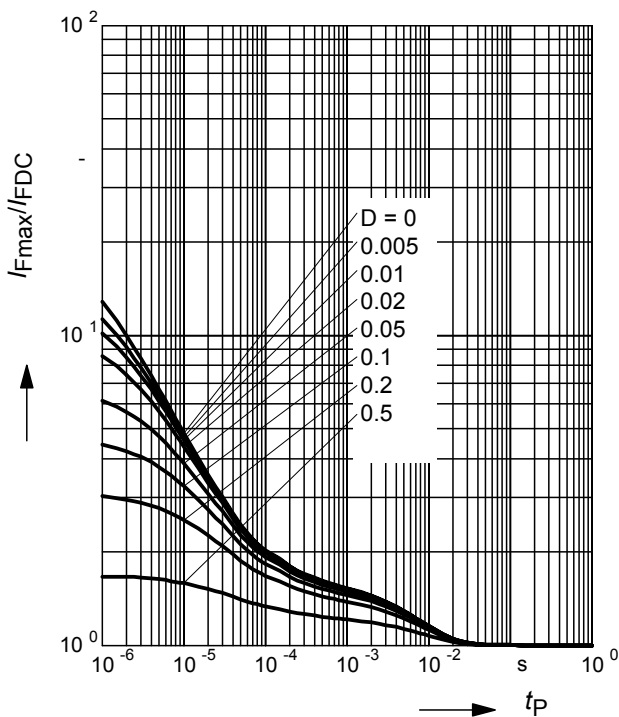
Permissible Puls Load $R_{thJS} = f(t_p)$

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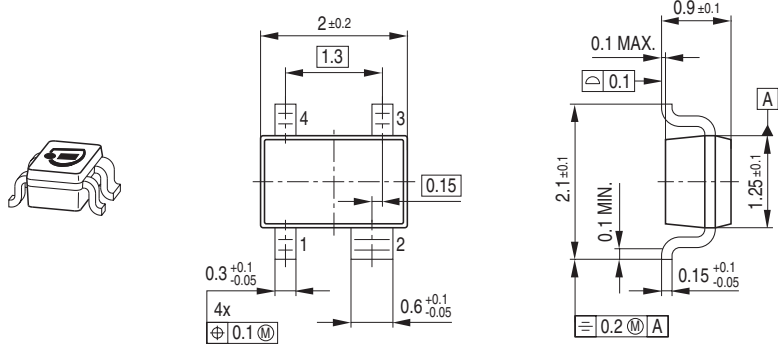


Permissible Pulse Load

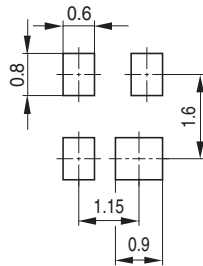
$I_{Fmax} / I_{FDC} = f(t_p)$ BAR81W



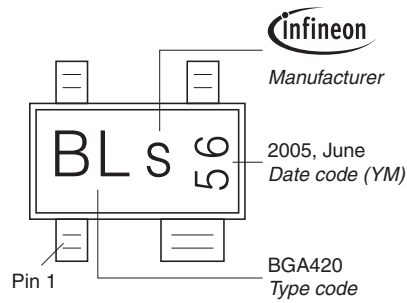
Package Outline



Foot Print

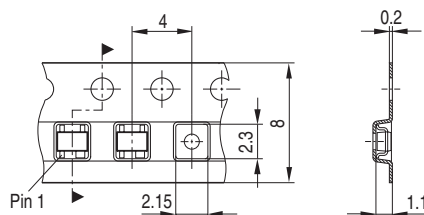


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



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